

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
6 May 2005 (06.05.2005)

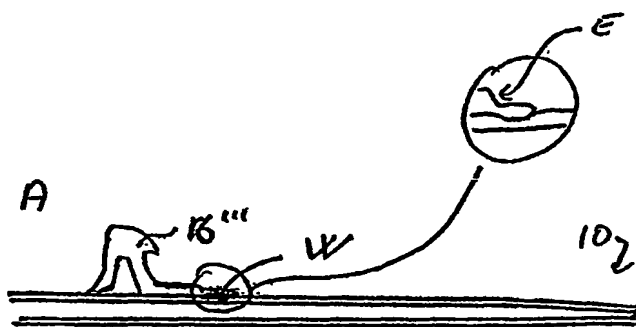
PCT

(10) International Publication Number  
**WO 2005/039861 A2**

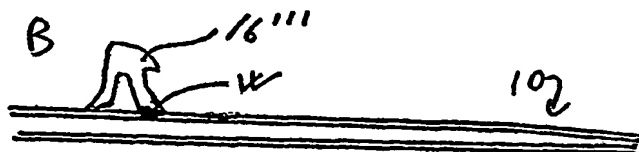
- (51) International Patent Classification<sup>7</sup>: **B29C 65/00**, A61F 5/448 (74) Agent: INSPICOS A/S; Bøge Allé 5, P.O. Box 45, DK-2970 Hørsholm (DK).
- (21) International Application Number: PCT/DK2004/000728 (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (22) International Filing Date: 21 October 2004 (21.10.2004)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:  
PA 2003 01571 24 October 2003 (24.10.2003) DK
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- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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(54) Title: AN OSTOMY MOUNTING WAFER AND A METHOD OF PREPARING IT



(57) Abstract: An ostomy body side mounting wafer and a method of preparing the ostomy body side mounting wafer, where the wafer is assembled from two parts using laser welding. The laser light is provided through one of the parts having a low or lower absorption of the laser light. The other part has a higher absorption of the laser light, whereby the interface between the two parts is heated at the welding zone(s) of the laser light. In this manner, an assembly is obtained independently of the thicknesses of the materials and even close to openings or other edges.





**Published:**

— without international search report and to be republished  
upon receipt of that report

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